

## **ATTENTION**

**OBSERVE PRECAUTIONS** FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

- •Super high flux output and high luminance.
- •Designed for high current operation.
- •Low thermal resistance.
- •Silicone resin with glass lens.
- •Compatible with IR-reflow processes.
- •ESD protection .
- •Package: 500pcs / reel.
- •RoHS compliant.

## AADG18080QR412S/3

## **SERIES**



## **Applications**

- Substitution of micro incandescent lamps.
- Portable light source.
- Signal and symbol luminaire for orientation.
- Marker lights (e.g. steps, exit ways, etc).
- Decorative and entertainment lighting.
- Commercial and residential lighting.
- Emergency-vehicle lighting.

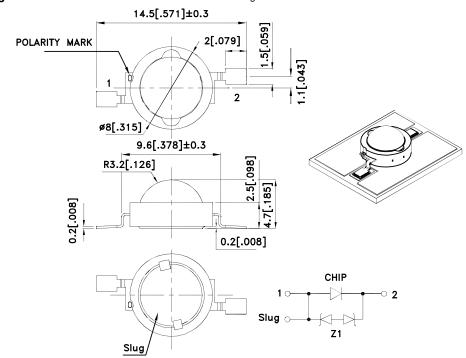
## **Application Note**

Static electricity and surge damage the LEDS.

It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.

All devices, equipment and machinery must be electrically grounded.

## **Package Dimensions**



- 1. All dimensions are in millimeters (inches).

- 2. Tolerance is ±0.25(0.01") unless otherwise noted.

  3. Specifications are subject to change without notice.

  4. The device has a single mounting surface. The device must be mounted according to the specifications.



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## Flux Characteristics at 700mA Ambient Temperature, T<sub>a</sub> = 25°C

Erp	Color	Part No.	Luminous Flux (lm) @ 700mA [1]			Typical Luminous Flux (lm) [1]	
			Code.	Min.	Max.	Тур.	
	Cool White (InGaN)	AADG18080QR412S/3-C1	C2	120	140	160	
1201200318			C3	140	160		
			C4	160	180		
			C5	180	210		
1201200326	Neutral White (InGaN)	AADG18080QR412S/3-N1	C1	100	120	140	
			C2	120	140		
			C3	140	160		
			C4	160	180		
1201200328	Warm White (InGaN)	AADG18080QR412S/3-W2	C1	100	120	140	
			C2	120	140		
			C3	140	160		
			C4	160	180		

### Note:

## Optical Characteristics at 700mA Ambient Temperature, $T_a = 25^{\circ}C$

Color		Correlated Color Temperature CCT	Typical Viewing Angle [1] (degrees)	
	Min.	Тур.	Max.	201/2
Cool White	5310K	6000K	7040K	100°
Neutral White	3710K	4500K	5310K	100°
Warm White	2580K	3000K	3710K	100°

### Note

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<sup>1.</sup> Minimum luminous flux performance guaranteed within published operating conditions. Kingbright maintains tolerance of +/-15% on flux.

<sup>1.</sup>Viewing angle is the off axis angle from lamp centerline where the luminous intensity is 1/2 of the peak value.



## Electrical Characteristics at 700mA Ambient Temperature, $T_a = 25$ °C

Part No.	Forward Voltage V <sub>f</sub> [1] (V)			Typical Temperature Coefficient of Forward Voltage [2] (mV/°C)	Typical Thermal Resistance (°C/W)	
	Min.	Тур.	Max.	$\Delta V_{\rm f}$ / $\Delta T$	$R_{thj-slug}$	
AADG18080QR412S/3-C1	-	4.6	5.2	-4.3	7	
AADG18080QR412S/3-N1	-	4.6	5.2	-4.3	7	
AADG18080QR412S/3-W2	-	4.6	5.2	-4.3	7	

## **Absolute Maximum Ratings**

Parameter	Cool White / Neutral White / Warm White				
DC Forward Current (mA) [1]	700				
Peak Pusled Forward Current (mA)	1000				
Average Forward Current (mA)	700				
Reverse Voltage (V)	5				
ESD Sensitivity	8000V HBM				
LED Junction Temperature (°C)	130				
Operation Temperature (°C)	-40 to+100				
Storage Temperature (°C)	-40 to+110				
Soldering Temperature (°C)	260 For 5 Seconds				

## **Moisture Sensitivity**

AADG18080 LEDs are packaged in airtight and moisture-resistant bags to prevent moisture absorption which may lead to catastrophic failure in reflow soldering process. Kingbright recommends that the devices must be baked before soldering if they are removed from the original package, and are exposed to environmental conditions for longer than the durations (unit: days) defined in the table below. Recommended baking conditions are 24 hours at 80°C.

Temperature	Maximum Percent Relative Humidity						
remperature	30%	40%	50%	60%	70%	80%	90%
30°C	9	5	4	3	1	1	1
25°C	12	7	5	4	2	1	1
20°C	17	9	7	6	2	2	1

## **Storage Conditions**

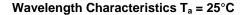
After being removed from the original sealed package, AADG18080 LEDs should be stored at a temperature of 25 °C with a relative humidity lower than 10%. Under such conditions, storage duration is excluded from the exposure duration as defined in the Moisture Sensitivity section.

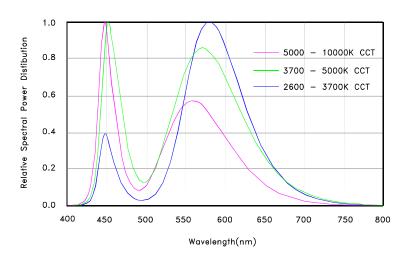
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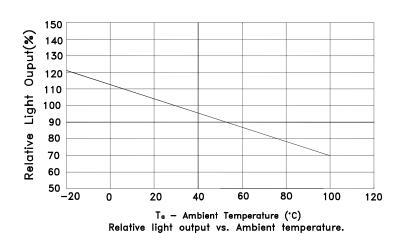
<sup>1.</sup>Kingbright maintains a tolerance of +/- 0.1V on forward voltage measurements. 2.Measured between 25 °C < TJ < 130 °C at IF = 700 mA.

<sup>1.</sup> Proper current derating must be observed to maintain junction temperature below the maximum.





## **Light Output Characteristics**

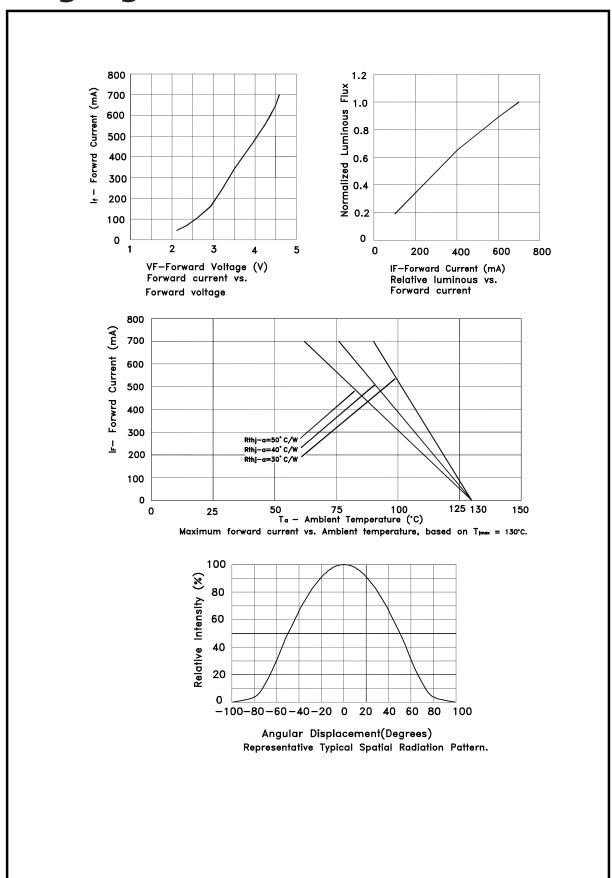


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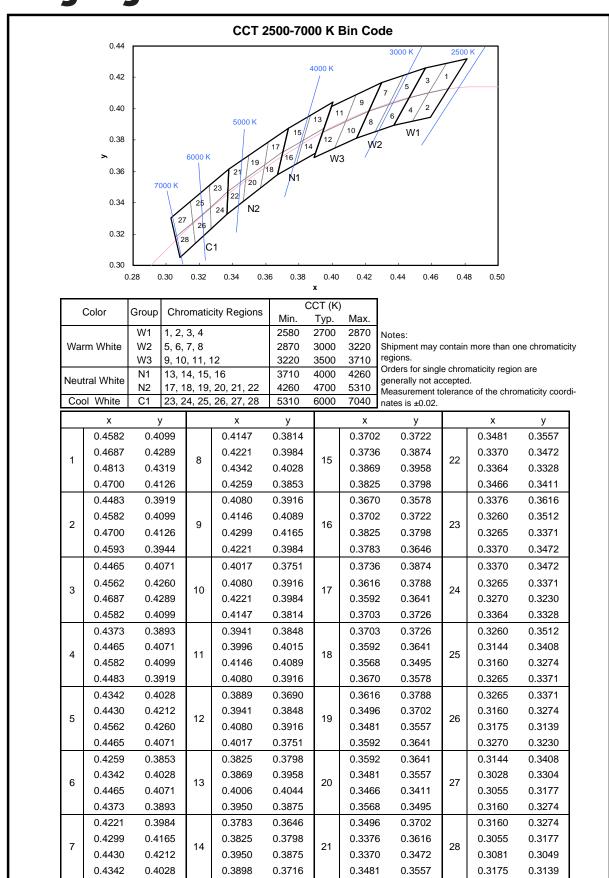


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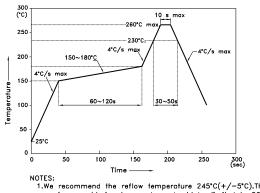


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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C. 2. Don't cause stress to the epoxy resin while it is exposed to high temperature.

3. Number of reflow process shall be 2 times or less.

## **Heat Generation:**

1.Thermal design of the end product is of paramount importance. Please consider the heat generation of the LED when making the system design. The coefficient of temperature increase per input electric power is affected by the thermal resistance of the circuit board and density of LED placement on the board, as well as other components. It is necessary to avoid intense heat generation and operate within the maximum ratings given in this specification.

2.Please determine the operating current with consideration of the ambient temperature local to the LED and refer to the plot of Permissible Forward current vs. Ambient temperature on CHARACTERISTICS in this specification. Please also take measures to remove heat from the area near the LED to improve the operational characteristics on the LED.

3.The equation ① indicates correlation between T<sub>j</sub> and Ta and the equation ② indicates correlation between T<sub>j</sub> and Ts

 $T_j = T_a + R_{thj-a} *W \dots$ 

Tj = Ts + Rthj-s \*W ...... 2

Tj = dice junction temperature:  $^{\circ}$ C

Ts = solder point temperature:°℃

Rthj-a = heat resistance from dice junction temperature to ambient temperature : °C /W

Rthj-s = heat resistance from dice junction temperature to Ts measuring point : °C /W

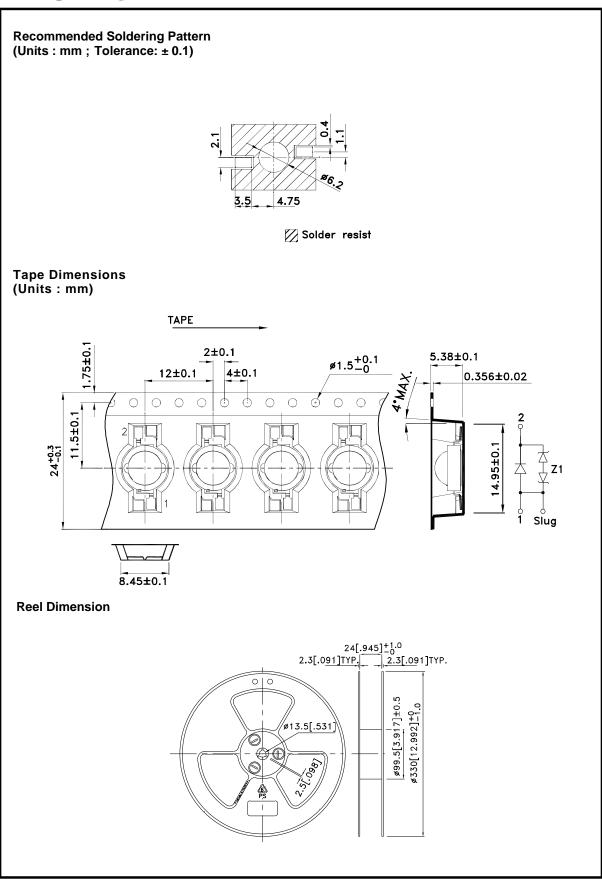
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W = inputting power (IFx VF) : W

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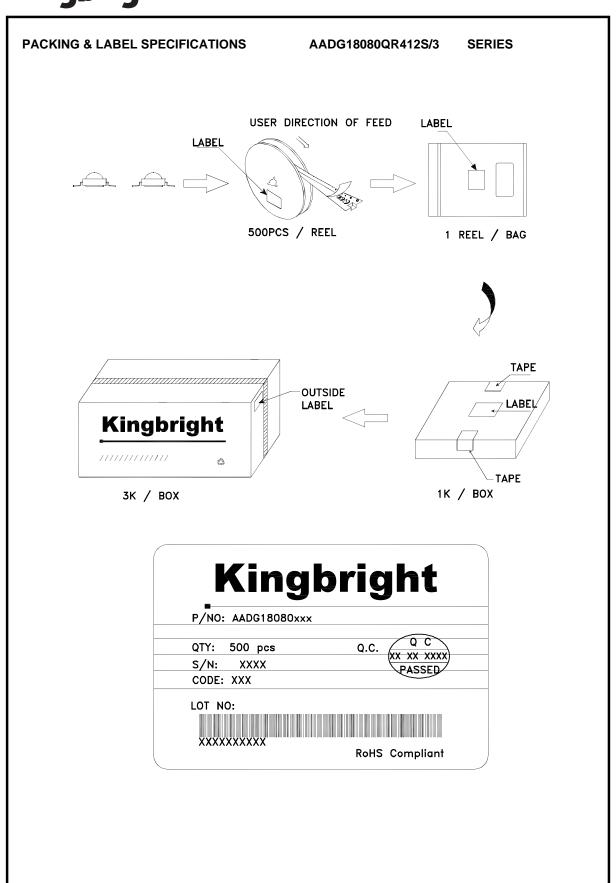
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